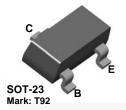


March 2014

BSR18A PNP General-Purpose Amplifier

Description

This device is designed as a general-purpose amplifier for switching applications at collector currents of 10 μ A to 100 mA. Sourced from process 66.



Ordering Information

Part Number	Marking	Package	Packing Method
BSR18A	T92	SOT-23 3L	Tape and Reel

Absolute Maximum Ratings(1),(2)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Value	Unit
V _{CEO}	Collector-Emitter Voltage	-40	V
V _{CBO}	Collector-Base Voltage -40		V
V _{EBO}	Emitter-Base Voltage	-5	V
I _C	Collector Current - Continuous	-200	mA
T _J , T _{STG}	Junction and Storage Temperature Range	-55 to +150	°C

Notes

- 1. These ratings are based on a maximum junction temperature of 150°C.
- These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty-cycle operations.

1

Thermal Characteristics(3)

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Max.	Unit
P _D	Total Device Dissipation	350	mW
	Derate Above T _A = 25°C	2.8	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

Note:

3. Device mounted on FR-4 PCB 40 mm X 40 mm X 1.5 mm.

Electrical Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage	$I_C = -10 \mu A, I_B = 0$	-40		V
V _{(BR)CBO}	Collector-Base Breakdown Voltage	$I_C = -1.0 \text{ mA}, I_E = 0$	-40		V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$I_E = -10 \mu A, I_C = 0$	-5.0		V
I _{CBO}	Collector Cut-Off Current	$V_{CB} = -30 \text{ V}, I_{E} = 0$		-50	nA
I _{EBO}	Emitter Cut-Off Current	$V_{EB} = -3.0 \text{ V}, I_{C} = 0$		-50	nA
h _{FE}		$I_C = -0.1 \text{ mA}, V_{CE} = -1.0 \text{ V}$	60		
		$I_C = -1.0 \text{ mA}, V_{CE} = -1.0 \text{ V}$	80		
	DC Current Gain ⁽⁴⁾	$I_C = -10 \text{ mA}, V_{CE} = -1.0 \text{ V}$	100	300	
		$I_C = -50 \text{ mA}, V_{CE} = -1.0 \text{ V}$	60		
		$I_C = -100 \text{ mA}, V_{CE} = -1.0 \text{ V}$	30		
\/ (aat)	Collector-Emitter Saturation Voltage ⁽⁴⁾	$I_C = -10 \text{ mA}, I_B = -1.0 \text{ mA}$		-0.25	V
V _{CE} (sat)		$I_C = -50 \text{ mA}, I_B = -5.0 \text{ mA}$		-0.40	V
\/ (aat)	Base-Emitter Saturation Voltage ⁽⁴⁾	$I_C = -10 \text{ mA}, I_B = -1.0 \text{ mA}$	-0.65	-0.85	V
V _{BE} (sat)		$I_C = -50 \text{ mA}, I_B = -5.0 \text{ mA}$		-0.95	
f _T	Transition Frequency	I_C = -10 mA, V_{CE} = -20 V, f = 100 MHz	250		MHz
C _{cb}	Collector-Base Capacitance	$V_{CB} = -5.0 \text{ V}, I_{E} = 0,$ f = 100 kHz		4.5	pF
C _{eb}	Emitter-Base Capacitance	$V_{EB} = -0.5 \text{ V, } I_{C} = 0,$ f = 100 kHz		10	pF
h _{ie}	Input Impedance	$V_{CE} = -10 \text{ V}, I_{C} = -1.0 \text{ mA},$ f = 1.0 kHz	2	12	kΩ
h _{ie}	Small-Signal Current Gain	$V_{CE} = -10 \text{ V}, I_{C} = -1.0 \text{ mA},$ f = 1.0 kHz	100	400	
h _{ie}	Output Admittance	$V_{CE} = -10 \text{ V}, I_{C} = -1.0 \text{ mA},$ f = 1.0 kHz	3	60	μS
t _d	Delay Time	$I_C = -10 \text{ mA}, I_{B1} = -1.0 \text{ mA},$		35	ns
t _r	Rise Time	V _{EB} = -0.5 V		35	ns
t _s	Storage Time	I _C = -10 mA,		275	ns
t _f	Fall Time	$I_{Bon} = I_{Boff} = -1.0 \text{ mA}$		75	ns

Note:

4. Pulse test: pulse width $300 \mu s$, duty cycle 0.01%.

2

Typical Performance Characteristics

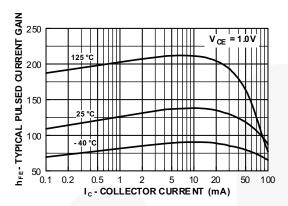


Figure 1. Typical Pulsed Current Gain vs. Collector Current

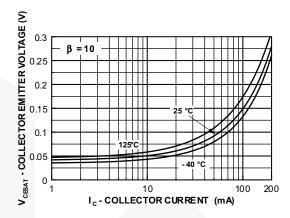


Figure 2. Collector-Emitter Saturation Voltage vs. Collector Current

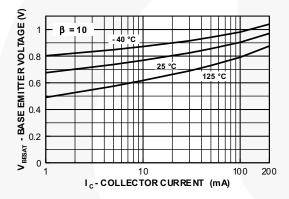


Figure 3. Base-Emitter Saturation Voltage vs. Collector Current

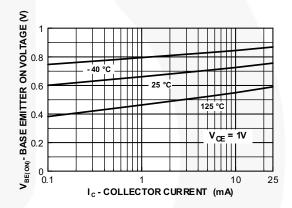


Figure 4. Base-Emitter On Voltage vs. Collector Current

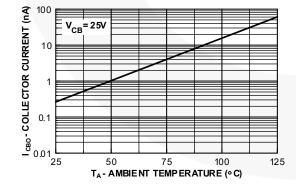


Figure 5. Collector Cut-Off Current vs.
Ambient Temperature

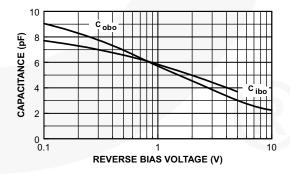


Figure 6. Common-Base Open Circuit Input and Output Capacitance vs. Reverse Bias Voltage

Typical Performance Characteristics (Continued)

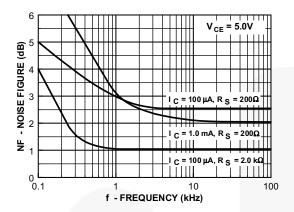


Figure 7. Noise Figure vs. Frequency

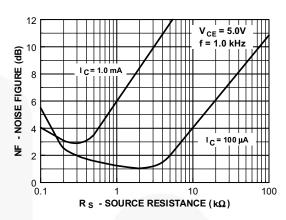


Figure 8. Noise Figure vs. Source Resistance

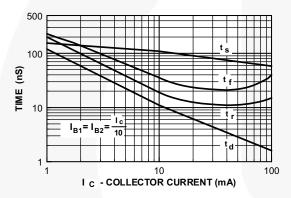


Figure 9. Switching Times vs. Collector Current

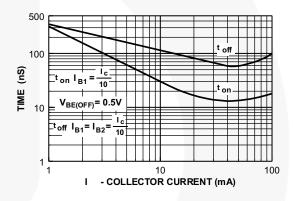


Figure 10. Turn-On and Turn-Off Times vs. Collector Current

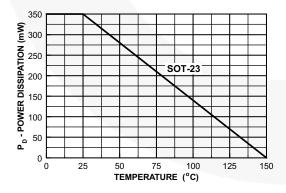


Figure 10. Power Dissipation vs. Ambient Temperature

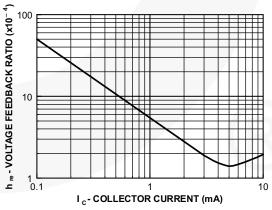


Figure 11. Voltage Feedback Ratio

Typical Performance Characteristics (Continued)

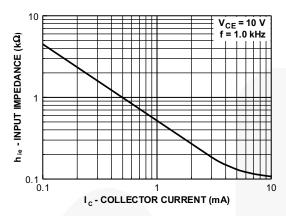


Figure 13. Input Impedance

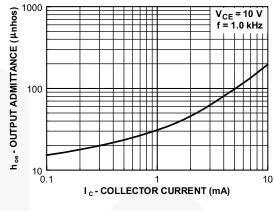


Figure 14. Output Admittance

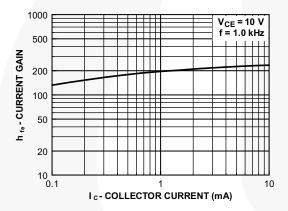


Figure 15. Current Gain

Physical Dimensions

0.95 2.92±0.20 3 1.40 1.30^{+0.20}_{-0.15} 2.20 0.60 0.37 (0.29) -0.95 ⊕ 0.20M A B 1.00 1.90 1.90 LAND PATTERN RECOMMENDATION 1.20 MAX SEE DETAIL A (0.93)0.10 ○ 0.10 M C C 2.40±0.30 NOTES: UNLESS OTHERWISE SPECIFIED **GAGE PLANE** A) REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H. B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.23 0.08 C) DIMENSIONS ARE INCLUSIVE OF BURRS, 0.25

SOT-23

Figure 16. 3-LEAD, SOT23, JEDEC TO-236, LOW PROFILE (ACTIVE)

SEATING PLANE MOLD FLASH AND TIE BAR EXTRUSIONS.

D) DIMENSIONING AND TOLERANCING PER

E) DRAWING FILE NAME: MA03DREV10

ASME Y14.5M - 1994.

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